IN THE SPECIFICATION:

Please amend the paragraphs starting at page 5, line 6, and ending at page 6, line 1, as follows.

--The present invention has been made to eliminate the conventional drawbacks, and has as its object to provide a multi-beam scanning apparatus which can be downsized and allows adjusting of the beam interval within a short time with high precision.

To achieve the above object, according to the present invention, there is provided a multi-beam scanning apparatus comprising a multi-beam light source unit having a multi-beam semiconductor laser and a laser holder holding the multi-beam semiconductor laser, scanning imaging means for scanning a plurality of laser beams emitted by the multi-beam semiconductor laser to form an image on a surface to be scanned, and a housing supporting the scanning imaging means and the multi-beam light source unit~~, wherein the~~. The multi-beam semiconductor laser is fixed to the laser holder with an inclination at or near a predetermined rotational angle for adjusting a beam interval between the plurality of laser beams.

In the multi-beam scanning apparatus, the multi-beam semiconductor laser preferably has a laser array fixed with an inclination with respect to a reference surface of the laser holder.--

Please amend the paragraph starting at page 6, line 9, and ending at line 24, as follows.

--In mounting the laser holder in the housing after the multi-beam semiconductor laser is fixed to the laser holder, the whole multi-beam light source unit is inclined (rotated) to adjust the beam interval. In this arrangement, however, angular adjustment is difficult to perform precisely, and ~~spends~~ takes a long time. In addition, an extra space is required to incline the large-area laser driving circuit board mounted on the multi-beam light source unit. To avoid this, in a unit assembly step of assembling the multi-beam semiconductor laser to the laser holder, the multi-beam semiconductor laser is rotated (inclined) through an angle necessary for adjusting the beam interval or an angle approximate to the necessary angle. In this state, the multi-beam semiconductor laser is fixed to the laser holder into a unit.--

Please amend the paragraph starting at page 7, line 20, and ending at page 8, line 12, as follows.

--To achieve the above object, according to the present invention, there is provided a multi-beam scanning apparatus comprising a multi-beam light source unit having a multi-beam semiconductor laser and a laser holder holding the multi-beam semiconductor, scanning imaging means for scanning a plurality of laser beams emitted by the multi-beam semiconductor laser to form an image on a surface to be scanned, a housing supporting the scanning imaging means and the multi-beam light source unit, and fixing means for fixing the multi-beam light source unit to the housing after the rotational

angle of the multi-beam light source unit is adjusted, the fixing means having a plurality of fixing ~~portions, wherein the~~ portions. The center of the rotation of the multi-beam light source unit and a plurality of emission points of the multi-beam semiconductor laser are located on a straight line connecting two of the plurality of fixing portions or a planar region defined by straight lines connecting all the plurality of fixing portions.--

Please amend the paragraphs starting at page 16, line 21, and ending at page 17, line 11, as follows.

--The edge-emission-type multi-beam semiconductor lasers 11 and 31 on each of which a plurality of emission points are aligned may be replaced with a multi-beam semiconductor laser 41 having a surface-emission-type laser chip 42 on which a plurality of emission points 42a to 42d are two-dimensionally arrayed, as shown in Fig. 10. This multi-beam semiconductor laser 41 can advantageously reduce optical aberration because all the emission points can be made close to the optical axis of the collimator lens. A positioning hole 41b is formed in a disk-like laser holder 41a as a positioning reference used to adjust the rotational angle θ for adjusting beam intervals T_1 to T_3.

The surface-emission-type laser can increase the degree of freedom for the positions of the emission points to facilitate distribution of the mounting tolerance.--

Please amend the paragraph starting at page 19, line 15, and ending at line 23, as follows.

--As shown in Fig. 11A, the three screws 14 fasten the laser holder 11a to the sidewall 8a of the optical box 8. Fixing portions 14a to 14c ~~by the screws 14~~ surround the emission points of the laser beams P_1 and P_2. That is, the three screws 14 are laid out to locate the emission points of the laser beams P_1 and P_2 on straight lines L_1 to L_3 connecting the fixing portions 14a to 14c or within a planar region N (shadow portion) defined by the straight line L_1 to L_3.--

Please amend the paragraph starting at page 20, line 13, and ending at line 18, as follows.

--Particularly, when the screws 14 are used as fixing means, the laser holder 11a and the sidewall 8a of the optical box 8 are pressed against each other via a fastening surface M. A clearance K is set as an adjustment margin for angular adjustment rotation. The laser holder 11a is moved within this range.--

Please amend the paragraph starting at page 21, line 26, and ending at page 22, line 7, as follows.

--Fig. 12 shows the fifth embodiment of the multi-beam light source unit. When the position of the emission point of a multi-beam semiconductor laser 11 is greatly ~~offsets~~ offset from the center O of rotation of a laser holder 11a due to low component precision, the multi-beam semiconductor laser 11 is adjusted again in the laser holder 11a.

To realize this, an adjustment member 15 for adjusting the relative position is used and fastened to the laser holder 11a with screws 16.--

Please amend the paragraphs starting at page 22, line 22, and ending at page 23, line 13, as follows.

--The edge-emission-type multi-beam semiconductor laser 11 on which a plurality of emission points are aligned may be replaced with a multi-beam semiconductor laser 41 having a surface-emission-type laser chip 42 on which a plurality of emission points 42a to 42d are two-dimensionally arrayed, as shown in Fig. 10. This multi-beam semiconductor laser 41 can advantageously reduce optical aberration because all the emission points can be made close to the optical axis of the collimator lens. A positioning hole 41b is formed in a disk-like laser holder 41a as a positioning reference used to adjust the inclination angle θ for adjusting line intervals T_1 to T_3.

The surface-emission-type laser can increase the degree of freedom for the positions of the emission points to facilitate distribution of the mounting tolerance.--